8-bit Proprietary Microcontroller cmos

F²MC-8L MB89650AR Series

MB89653AR/655AR/656AR/657AR/P657A MB89PV650A

■ DESCRIPTION

The MB89650AR series has been developed as a general-purpose version of the F²MC*-8L family consisting of proprietary 8-bit, single-chip microcontrollers.

In addition to a compact instruction set, the microcontrollers contain a variety of peripheral functions such as dual-clock control system, five operating speed control stages, timers, PWM timers, a serial interface, an A/D converter, external interrupts, an LCD controller/driver, and a watch prescaler.

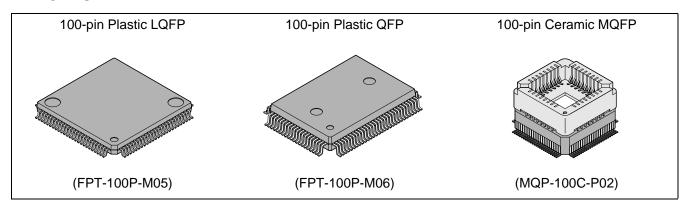
*: F2MC stands for FUJITSU Flexible Microcontroller.

■ FEATURES

- F2MC-8L family CPU core
- Dual-clock control system
- Maximum memory space: 64 Kbytes
- Minimum execution time: 0.4 μs/10 MHz
- Interrupt processing time: 3.6 μs/10 MHz
- I/O ports: Max 64 channels
- 21-bit time-base counter

(Continued)

PACKAGE





(Continued)

- 8-bit PWM timers: 2 channels (A maximum of 4 channels can be used for output.)
- 8/16-bit timer/counter: 4 channels (16 bits × 2 channels)
- 8-bit serial I/O: 1 channel
- 8-bit A/D converter: 8 channels
- External interrupt 1
 - Four independent channels with edge detection function
- External interrupt 2 (wake-up function)
 Twelve "L" level-interrupt channels
- Watch prescaler
- LCD controller/driver: 16 to 32 segments × 2 to 4 commons
- Power-on reset function
- Low-power consumption modes (subclock mode, watch mode, sleep mode, and stop mode)
- LQFP-100 and QFP-100 packages

■ PRODUCT LINEUP

Part number Parameter	MB89653AR	MB89655AR	MB89656AR	MB89657AR	MB89P657A	MB89PV650A		
Classification	Mass production products (mask ROM products)				One-time PROM product	Piggyback/ evaluation product (for evaluation and development)		
ROM size	8 K × 8 bits (internal mask ROM)	16 K × 8 bits (internal mask ROM)	24 K × 8 bits (internal mask ROM)	32 K × 8 bits (internal mask ROM)	32 K × 8 bits (internal PROM, programming with general- purpose EPROM programmer)	32 K × 8 bits (external ROM)		
RAM size	256 × 8 bits	512 × 8 bits	768 × 8 bits		1 K × 8 bits			
LCD display RAM			16:	× 8 bits				
CPU functions	Instruc Instruc Data b Minimu	Number of instructions : 136 Instruction bit length : 8 bits Instruction length : 1 to 3 bytes Data bit length : 1, 8, 16 bits Minimum execution time : 0.4 μs/10 MHz to 6.4 μs/10 MHz, 61.0 μs/32.768 kHz Interrupt processing time : 3.6 μs/10 MHz to 57.6 μs/10 MHz, 549.3 μs/32.768 kHz						
Ports	Input p Output I/O por Total	ports	: 8 (All als	: 8 (All also serve as peripherals.): 8 (All also serve as peripherals.): 48 (All also serve as peripherals.): 64				
8-bit timer 1, 8-bit timer 2		8-bit timer operation (toggled output capable, operating clock cycle: 0.8 to 12.8 μs) 16-bit timer operation (toggled output capable, operating clock cycle: 0.8 to 12.8 μs) 2 output channels are enabled when operating as an 8-bit timer.						
						(Continued)		

(Continued)

Part number Parameter	MB89653AR	MB89655AR	MB89656AR	MB89657AR	MB89P657A	MB89PV650A			
8-bit timer 3, 8-bit timer 4	16-bit time	8-bit timer operation (toggled output capable, operating clock cycle: 0.8 to 12.8 μs) 16-bit timer operation (toggled output capable, operating clock cycle: 0.8 to 12.8 μs) 2 output channels are enabled when operating as an 8-bit timer.							
Clock timer		21 bits × 1 (i	n main clock m	ode)/15 bits $ imes$ 1	(at 32.768 kHz)				
8-bit PWM timer 1, 8-bit PWM timer 2	8-k	oit resolution P	WM operation (conversion cyc	ing clock cycle: 0 le: 102 µs to 839 an output 2 char	ms)			
8-bit serial I/O	(one	8 bits LSB first/MSB first selectability One clock selectable from four transfer clocks (one external shift clock, three internal shift clocks: 0.8 μs, 3.2 μs, 12.8 μs)							
8-bit A/D converter		8-bit resolution × 8 channels A/D conversion mode (conversion time: 18 μs) Sense mode (conversion time: 5 μs) Continuous activation by an internal timer capable Reference voltage input							
External interrupt 1	Used also for v	R	tising edge/falli	nnels (edge se ng edge selecta . (Edge detection		ed in stop mode.)			
External interrupt 2 (wake-up function)		"L" level interrupt × 12 channels							
Standby mode	Subclock mode, sleep mode, watch mode, and stop mode								
Process		CMOS							
Operating voltage*	2.2 V to 6.0 V 2.7 V to 6.0 V					o 6.0 V			
EPROM for use			_			MBM27C256A- 20TVM			

^{*:} Varies with conditions such as the operating frequency. (See section "■ Electrical Characteristics".) In the case of the MB89PV650A, the voltage varies with the restrictions of the EPROM for use.

■ PACKAGE AND CORRESPONDING PRODUCTS

Package	MB89653AR MB89655AR MB89656AR MB89657AR MB89P657A	MB89PV650A
FPT-100P-M05	0	×
FPT-100P-M06	0	×
MQP-100C-P02	×	0

 \bigcirc : Available \times : Not available

Note: For more information about each package, see section "■ Package Dimensions".

■ DIFFERENCES AMONG PRODUCTS

1. Memory Size

Before evaluating using the piggyback product, verify its differences from the product that will actually be used. Take particular care on the following points:

- On the MB89653AR, the upper half of the register bank cannot be used.
- On the MB89P657A, the program area starts from address 8006_H but on the MB89PV650A and MB89657AR starts from 8000_H.

(On the MB89P657A, addresses 8000_H to 8005_H comprise the option setting area, option settings can be read by reading these addresses. On the MB89PV650A and MB89657A, addresses 8000_H to 8005_H could also be used as a program ROM. However, do not use these addresses in order to maintain compatibility of the MB89P657A.)

• The stack area, etc., is set at the upper limit of the RAM.

2. Current Consumption

- In the case of the MB89PV650A, add the current consumed by the EPROM which is connected to the top socket.
- When operated at low speed, the product with an OTPROM (one-time PROM) or an EPROM will consume more current than the product with a mask ROM.

However, the current consumption in sleep/stop modes is the same. (For more information, see sections "■ Electrical Characteristics" and "■ Example Characteristics.")

3. Mask Options

Functions that can be selected as options and how to designate these options vary by the product.

Before using options check section "■ Mask Options."

Take particular care on the following points:

- A pull-up resistor cannot be set for P70 to P75 on the MB89P657A. On this product, a pull-up resistor must be selected in a group of four bits for P14 to P17, P40 to P43, and P44 to P47.
- A pull-up resistor is not selectable for P30 to P37 and P40 to P47 if they are used as LCD pins.
- Options are fixed on the MB89PV650A.

4. Differences between the MB89650A and MB89650AR Series

- Electrical specifications/electrical characteristics
 - Electrical specifications of the MB89650AR series are the same with that of the MB89650A series.
 - Electrical characteristics of both series are much the same.
- Oscillation circuit type
 - In the MB89650A series, the circuit type of using an external clock differs from that of using a crystal or ceramic resonator as follows.
 - Circuit type of the MB89650AR series is a circuit type in using external clock even when crystal or ceramic resonator is selected.
- Memory access area and other specifications of both the MB89650A and MB89650AR series are the same.

• I/O circuit type

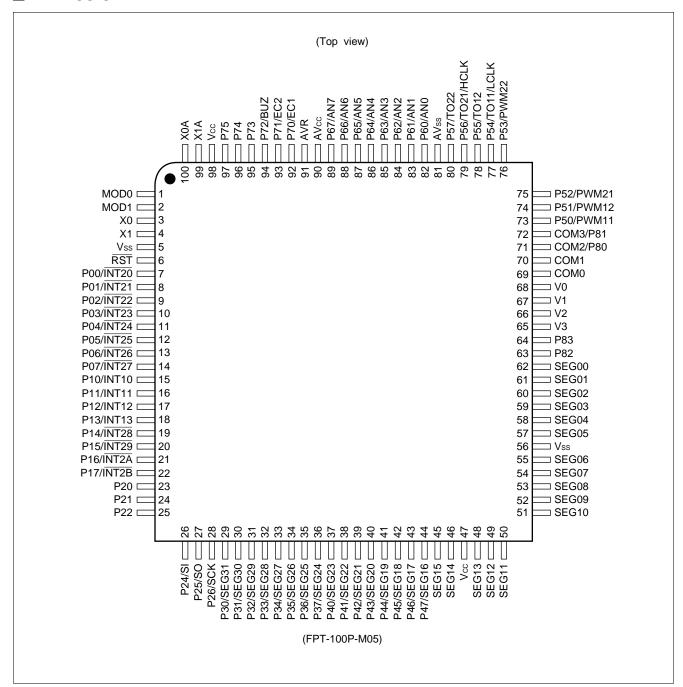
Туре	Circuit	Remarks
	X1 X0 X0 X1 X1 X0 X1 X1 X1 X1 X1 X1 X1 X1 X1 X1 X1 X1 X1	 Crystal or ceramic oscillation type (main clock) MB89PV650A and MB89P657A, external clock input selection versions of MB89653A/655A/656A/657A At an oscillation feedback resistor of approximately 1 MΩ/5.0 V MB89653AR/655AR/656AR/657AR
A	X1 X0 X0 X0 X1 X0 X1 X1 X1 X1 X1 X1 X1 X1 X1 X1 X1 X1 X1	 Crystal or ceramic oscillation type (main clock) Crystal or ceramic oscillation selection versions of MB89653A/655A/656A/657A At an oscillation feedback resistor of approximately 1 MΩ/5.0 V

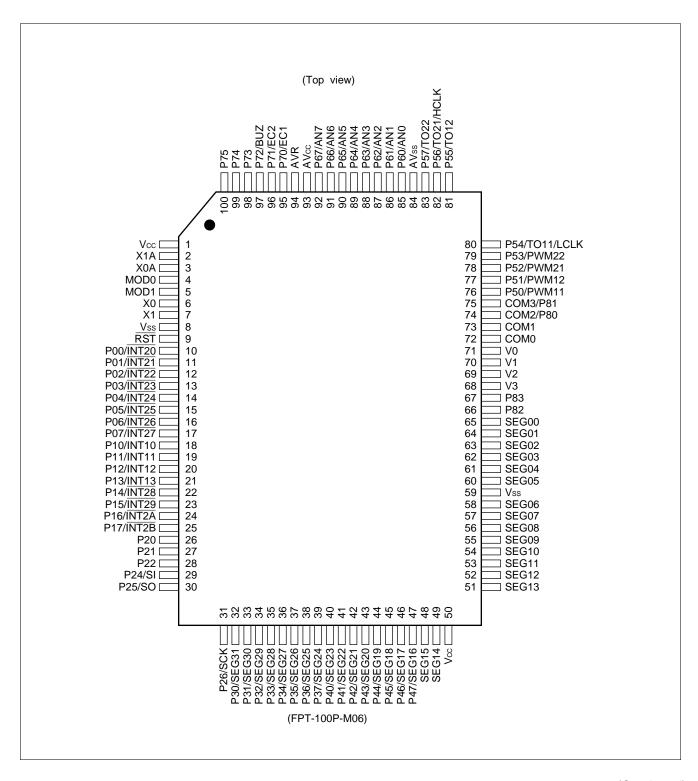
■ CORRESPONDENCE BETWEEN THE MB89650A AND MB89650AR SERIES

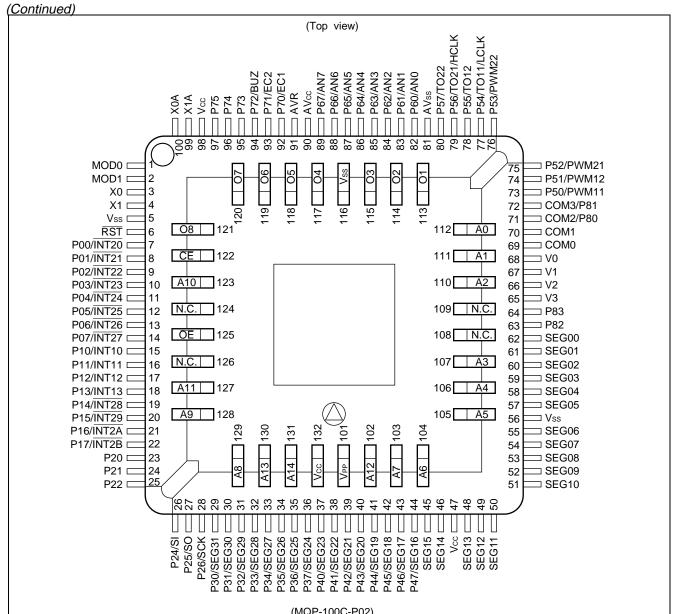
- The MB89650AR series is the reduction version of the MB89650A series.
- The MB89650A and MB89650AR series consist of the following products:

MB89650A series	MB89653A	MB89655A	MB89656A	MB89657A	MB89P657A	MB89PV650A
MB89650AR series	MB89653AR	MB89655AR	MB89656AR	MB89657AR	WB001 007A	WIDOST VOCOA

■ PIN ASSIGNMENT







(MQP-100C-P02)

Pin assignment on package top (MB89PV650A only)

Pin no.	Pin name	Pin no.	Pin name	Pin no.	Pin name	Pin no.	Pin name
101	V _{PP}	109	N.C.	117	O4	125	ŌĒ
102	A12	110	A2	118	O5	126	N.C.
103	A7	111	A1	119	O6	127	A11
104	A6	112	A0	120	07	128	A9
105	A5	113	01	121	O8	129	A8
106	A4	114	O2	122	CE	130	A13
107	А3	115	O3	123	A10	131	A14
108	N.C.	116	Vss	124	N.C.	132	Vcc

N.C.:Internally connected. Do not use.

■ PIN DESCRIPTION

Pin no.			Circuit	
QFP*1	MQFP*2 LQFP*3	Pin name	Circuit type	Function
4	1	MOD0	J	Operating mode selection pins
5	2	MOD1		Connect to Vss (GND) when using.
6	3	X0	А	Main clock crystal oscillator pins (Max 10 MHz)
7	4	X1		ivialit clock crystal oscillator pins (wax 10 ivii 12)
8	5	Vss	_	Power supply (GND) pin
9	6	RST	J	Reset input pin
10 to 17	7 to 14	P00/ <u>INT20</u> to P07/ <u>INT27</u>	F	General-purpose I/O ports Also serve as an external interrupt 2 input (wake-up function). External interrupt 2 input (INT20 to INT27) is hysteresis input while port input (P00 to P07) is CMOS input.
18 to 21	15 to 18	P10/INT10 to P13/INT13	F	General-purpose I/O ports Also serve as an external interrupt 1 input. External interrupt 1 input (INT10 to INT13) is hysteresis input while port input (P10 to P13) is CMOS input.
22 to 25	19 to 22	P14/INT28 to P15/INT2B	F	General-purpose I/O ports Also serve as an external interrupt 2 input (wake-up function). External interrupt 2 input (INT28 to INT2B) is hysteresis input while port input (P14 to P17) is CMOS input.
26 to 28	23 to 25	P20 to P22	С	General-purpose I/O ports
29, 30, 31	26, 27, 28	P24/SI, P25/SO, P26/SCK	F	General-purpose I/O ports The output type can be switched between N-ch opendrain and CMOS. These ports also serve as an 8-bit serial I/O. The P26/SCK pin is a CMOS input type when it functions as the port input (P26) while the pin is a hysteresis input type when it functions as the serial clock input (SCK).
32 to 47	29 to 44	P36/SEG31 to P47/SEG26	Н	General-purpose I/O ports Also serve as an LCD controller/driver segment output.
48, 49	45, 46	SEG15, SEG14	I	LCD controller/driver segment output pins

*1: FPT-100P-M06

*2: FPT-100P-M05

*3: MQP-100C-P02

(Continued)

Pin no.			O::4	Function		
QFP*1	MQFP*2 LQFP*3	Pin name Circuit type				
50	47	Vcc	_	Power supply pin		
51 to 58	48 to 55	SEG13 to SEG06	I	LCD controller/driver segment output pins		
59	56	Vss		Power supply (GND) pin		
60 to 65	57 to 62	SEG05 to SEG00	I	LCD controller/driver segment output pins		
66, 67	63, 64	P82, P83	С	General-purpose I/O ports		
68 to 71	65 to 68	V3 to V0	_	LCD driving power supply pins		
72, 73	69, 70	COM0, COM1	I	LCD controller/driver common output pins		
74, 75	71, 72	COM2/P80, COM3/P81	Н	General-purpose I/O ports Also serve as an LCD controller/driver common output.		
76 to 79	73 to 76	P50/PWM11 to P53/PWM22	G	General-purpose output ports Also serve as an 8-bit PWM timer.		
80, 81, 82, 83	77, 78, 79, 80	P54/TO11/LCLK, P55/TO12, P56/TO21/HCLK, P57/TO22	G	General-purpose output ports Also serve as an 8/16-bit timer. P54 and P56 also serve as a 32.768 kHz oscillation output/10 MHz divide-by-two output.		
84	81	AVss		A/D converter power supply (GND) pin		
85 to 92	82 to 89	P60/AN0 to P67/AN7	Е	General-purpose input ports Also serve as an analog input.		
93	90	AVcc	_	A/D converter power supply pin		
94	91	AVR	_	A/D converter reference voltage input pin		
95, 96	92, 93	P70/EC1, P71/EC2	К	General-purpose N-ch open-drain I/O ports Also serve as an 8/16-bit timer to input hysteresis.		
97, 98 to 100	94, 95 to 97	P72/BUZ, P73 to P75	D	General-purpose N-ch open-drain I/O ports P72 also serves as a buzzer output.		
1	98	Vcc	_	Power supply pin		
2	99	X1A	В	Subplicate arriatal applilator pine (22.769 kHz)		
3	100	X0A	В	Subclock crystal oscillator pins (32.768 kHz)		

*1: FPT-100P-M06

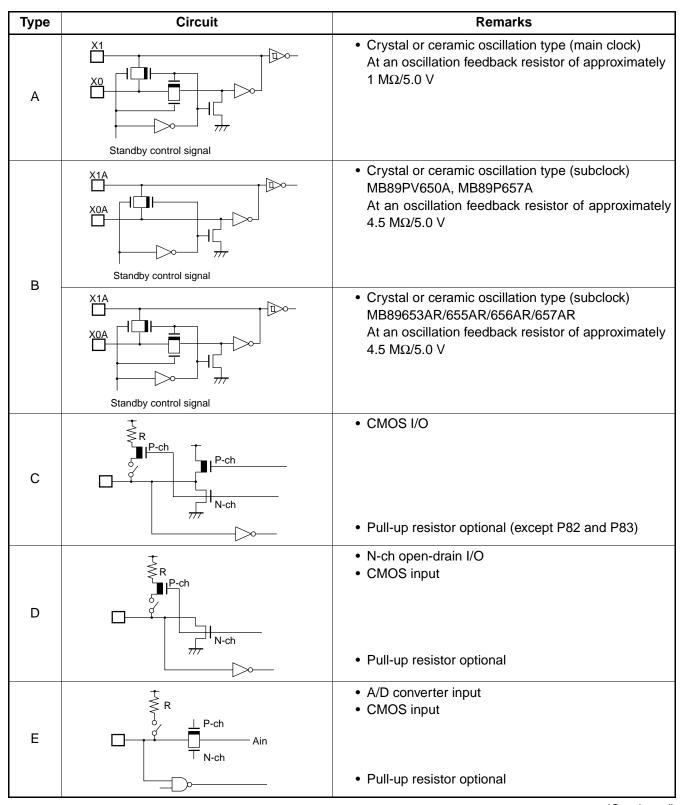
*2 : FPT-100P-M05

*3: MQP-100C-P02

• External EPROM pins (MB89PV650A only)

Pin no.	Pin name	I/O	Function
101	V _{PP}	0	"H" level output pin
102 103 104 105 106 107 110 111	A12 A7 A6 A5 A4 A3 A2 A1 A0	О	Address output pins
113 114 115	O1 O2 O3	I	Data input pins
116	Vss	0	Power supply (GND) pin
117 118 119 120 121	O4 O5 O6 O7 O8	I	Data input pins
122	CE	0	ROM chip enable pin Outputs "H" during standby.
123	A10	0	Address output pin
125	ŌĒ	0	ROM output enable pin Outputs "L" at all times.
127 128 129	A11 A9 A8	0	Address output pins
130	A13	0	Address output pin
131	A14	0	Address output pin
132	Vcc	0	EPROM power supply pin
108 109 124 126	N.C.	_	Internally connected pins Be sure to leave them open.

■ I/O CIRCUIT TYPE



Type	Circuit	Remarks
F	P-ch N-ch	 CMOS I/O (when selected as general-purpose ports) P24 to P26 outputs can be switched between CMOS and N-ch open-drain. When toggled as hysteresis input peripherals. However, SI input excluded. Pull-up resistor optional
		CMOS output
G	P-ch N-ch	
Н	P-ch N-ch N-ch N-ch N-ch N-ch	LCD controller/driver output CMOS I/O Pull-up resistor optional
I	P-ch N-ch N-ch N-ch	LCD controller/driver output
J		
К	R P-ch	 Hysteresis input N-ch open-drain output Pull-up resistor optional

HANDLING DEVICES

1. Preventing Latchup

Latchup may occur on CMOS ICs if voltage higher than Vcc or lower than Vss is applied to input and output pins other than medium- to high-voltage pins or if higher than the voltage which shows on "1. Absolute Maximum Ratings" in section "■ Electrical Characteristics" is applied between Vcc and Vss.

When latchup occurs, power supply current increases rapidly and might thermally damage elements. When using, take great care not to exceed the absolute maximum ratings.

Also, take care to prevent the analog power supply (AVcc and AVR) and analog input from exceeding the digital power supply (Vcc) when the analog system power supply is turned on and off.

2. Treatment of Unused Input Pins

Leaving unused input pins open could cause malfunctions. They should be connected to a pull-up or pull-down resistor.

3. Treatment of Power Supply Pins on Microcontrollers with A/D and D/A Converters

Connect to be AVcc = DAVC = Vcc and AVss = AVR = Vss even if the A/D and D/A converters are not in use.

4. Treatment of N.C. Pins

Be sure to leave (internally connected) N.C. pins open.

5. Power Supply Voltage Fluctuations

Although Vcc power supply voltage is assured to operate within the rated range, a rapid fluctuation of the voltage could cause malfunctions, even if it occurs within the rated range. Stabilizing voltage supplied to the IC is therefore important. As stabilization guidelines, it is recommended to control power so that Vcc ripple fluctuations (P-P value) will be less than 10% of the standard Vcc value at the commercial frequency (50 to 60 Hz) and the transient fluctuation rate will be less than 0.1 V/ms at the time of a momentary fluctuation such as when power is switched.

6. Precautions when Using an External Clock

Even when an external clock is used, oscillation stabilization time is required for power-on reset (optional) and wake-up from stop mode.

■ PROGRAMMING TO THE EPROM ON THE MB89P657A

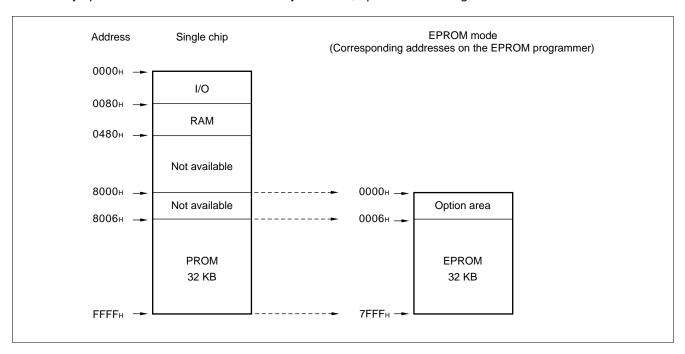
The MB89P657A is an OTPROM version of the MB89650A series.

1. Features

- 32-Kbyte PROM on chip
- Options can be set using the EPROM programmer.
- Equivalency to the MBM27C256A in EPROM mode (when programmed with the EPROM programmer)

2. Memory Space

Memory space in each mode such as 32-Kbyte PROM, option area is diagrammed below.



3. Programming to the EPROM

In EPROM mode, the MB89P657A functions equivalent to the MBM27C256A. This allows the PROM to be programmed with a general-purpose EPROM programmer (the electronic signature mode cannot be used) by using the dedicated socket adapter.

When the operating ROM area for a single chip is 32 Kbytes (8006_H to FFFF_H) the PROM can be programmed as follows:

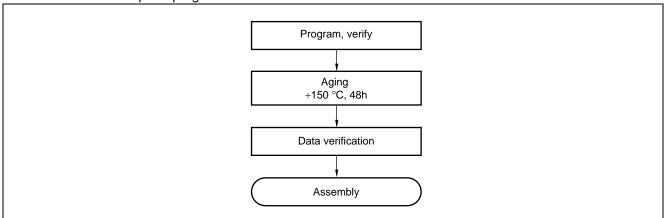
Programming procedure

- (1) Set the EPROM programmer to the MBM27C256A.
- (2) Load program data into the EPROM programmer at 0006_H to 7FFF_H (note that addresses 8006_H to FFFF_H while operating as a single chip assign to 0006_H to 7FFF_H in EPROM mode).

 Load option data into addresses 0000_H to 0005_H of the EPROM programmer. (For information about each corresponding option, see "7. Setting OTPROM Options.")
- (3) Program to 0000H to 7FFFH with the EPROM programmer.

4. Recommended Screening Conditions

High-temperature aging is recommended as the pre-assembly screening procedure for a product with a blanked OTPROM microcomputer program.



5. Programming Yield

All bits cannot be programmed at Fujitsu shipping test to a blanked OTPROM microcomputer, due to its nature. For this reason, a programming yield of 100% cannot be assured at all times.

6. EPROM Programmer Socket Adapter

Package	Compatible socket adapter
FPT-100P-M05	ROM-100SQF-28DP-8L
FPT-100P-M06	ROM-100QF-28DP-8L2

Inquiry: Sun Hayato Co., Ltd.: TEL 81-3-3802-5760

Note: Connect the ROM-100SQF-28DP-8L jumper pin to Vss when using.

Depending on the EPROM programmer, inserting a capacitor of about 0.1 μ F between V_{PP} and V_{SS} or V_{CC} and V_{SS} can stabilize programming operations.

7. Setting OTPROM Options

The programming procedure is the same as that for the PROM. Options can be set by programming values at the addresses shown on the memory map. The relationship between bits and options is shown on the following bit map:

• OTPROM option bit map

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0000н	Vacancy Readable and writable	Vacancy Readable and writable	P81 Pull-up 1: No 0: Yes	P80 Pull-up 1: No 0: Yes	Single/dual- clock system 1: Dual clock 2: Single clock			
0001н	P07	P06	P05	P04	P03	P02	P01	P00
	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up
	1: No	1: No	1: No	1: No	1: No	1: No	1: No	1: No
	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes
0002н	P37	P36	P35	P34	P33	P32	P31	P30
	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up
	1: No	1: No	1: No	1: No	1: No	1: No	1: No	1: No
	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes
0003н	P67	P66	P65	P64	P63	P62	P61	P60
	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up
	1: No	1: No	1: No	1: No	1: No	1: No	1: No	1: No
	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes
0004н	P47 to P44	P43 to P40	P26	P25	P24	P22	P21	P20
	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up	Pull-up
	1: No	1: No	1: No	1: No	1: No	1: No	1: No	1: No
	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes	0: Yes
0005н	Vacancy Readable and writable	Vacancy Readable and writable	Vacancy Readable and writable	P17 to P14 Pull-up 1: No 0: Yes	P13 Pull-up 1: No 0: Yes	P12 Pull-up 1: No 0: Yes	P11 Pull-up 1: No 0: Yes	P10 Pull-up 1: No 0: Yes

Notes: • Set each bit to 1 to erase.

• Do not write 0 to the vacant bit.

The read value of the vacant bit is 1, unless 0 is written to it.

■ PROGRAMMING TO THE EPROM WITH PIGGYBACK/EVALUATION DEVICE

1. EPROM for Use

MBM27C256A-20TVM

2. Programming Socket Adapter

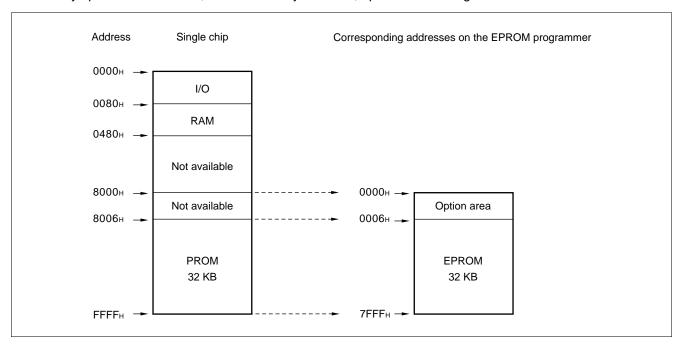
To program to the PROM using an EPROM programmer, use the socket adapter (manufacturer: Sun Hayato Co., Ltd.) listed below.

Package	Adapter socket part number
LCC-32(Rectangle)	ROM-32LC-28DP-YG
LCC-32(Square)	ROM-32LC-28DP-S

Inquiry: Sun Hayato Co., Ltd.: TEL 81-3-3802-5760

3. Memory Space

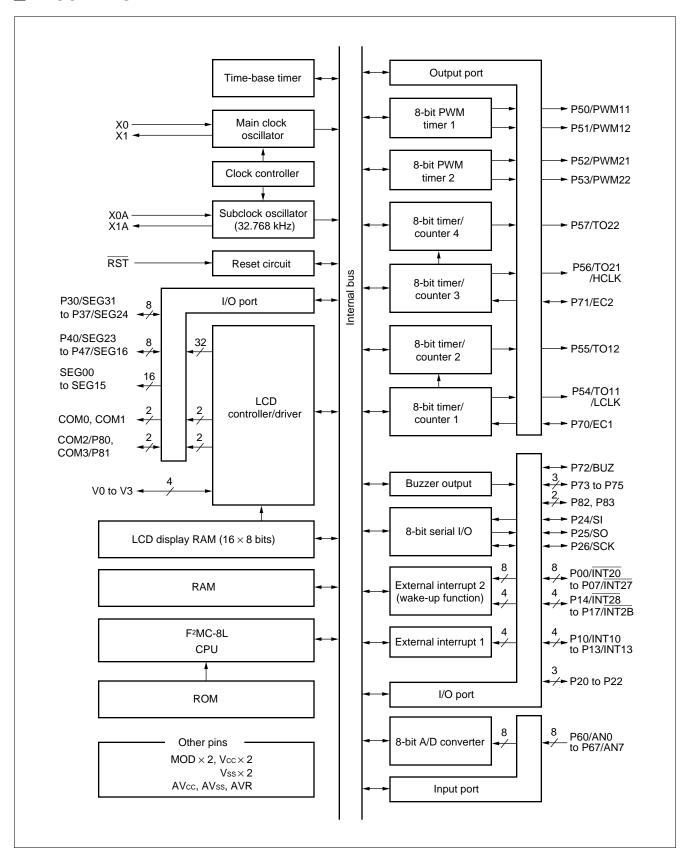
Memory space in each mode, such as 32-Kbyte PROM, option area is diagrammed below.



4. Programming to the EPROM

- (1) Set the EPROM programmer to the MBM27C256A.
- (2) Load program data into the EPROM programmer at 0006H to 7FFFH.
- (3) Program to 0000 H to 7FFF H with the EPROM programmer.

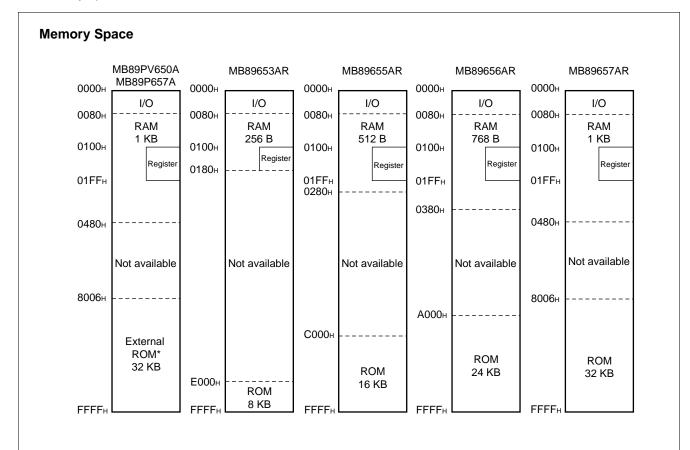
■ BLOCK DIAGRAM



■ CPU CORE

1. Memory Space

The microcontrollers of the MB89650AR series offer a memory space of 64 Kbytes for storing all of I/O, data, and program areas. The I/O area is located at the lowest address. The data area is provided immediately above the I/O area. The data area can be divided into register, stack, and direct areas according to the application. The program area is located at exactly the opposite end, that is, near the highest address. Provide the tables of interrupt reset vectors and vector call instructions toward the highest address within the program area. The memory space of the MB89650AR series is structured as illustrated below.



^{*:} This is an internal PROM on the MB89P657A.

Since addresses 8000H to 8005H for the MB89P657A comprise an option area, do not use this area for the MB89PV650A.

2. Registers

The F²MC-8L family has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The following dedicated registers are provided:

Program counter (PC): A 16-bit register for indicating instruction storage positions

Accumulator (A): A 16-bit temporary register for storing arithmetic operations, etc. When the

instruction is an 8-bit data processing instruction, the lower byte is used.

Temporary accumulator (T): A 16-bit register which performs arithmetic operations with the accumulator

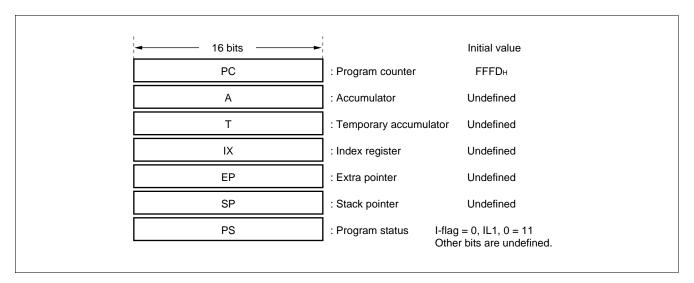
When the instruction is an 8-bit data processing instruction, the lower byte is used.

Index register (IX): A 16-bit register for index modification

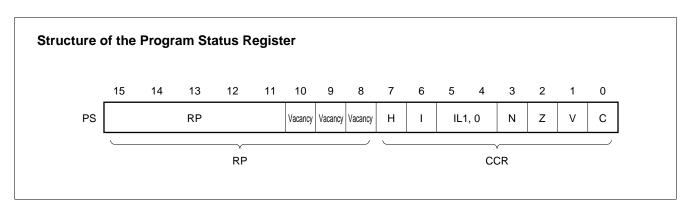
Extra pointer (EP): A 16-bit pointer for indicating a memory address

Stack pointer (SP): A 16-bit register for indicating a stack area

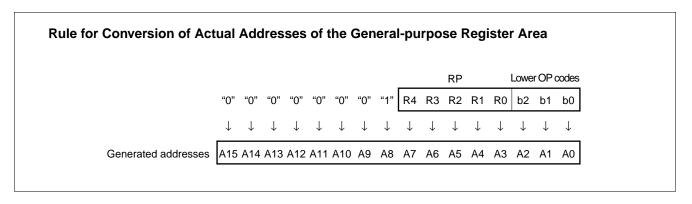
Program status (PS): A 16-bit register for storing a register pointer, a condition code



The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and the lower 8 bits for use as a condition code register (CCR). (See the diagram below.)



The RP indicates the address of the register bank currently in use. The relationship between the pointer contents and the actual address is based on the conversion rule illustrated below.



The CCR consists of bits indicating the results of arithmetic operations and the contents of transfer data and bits for control of CPU operations at the time of an interrupt.

- H-flag: Set when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation. Cleared otherwise. This flag is for decimal adjustment instructions.
- I-flag: Interrupt is allowed when this flag is set to 1. Interrupt is prohibited when the flag is set to 0. Set to 0 when reset.
- IL1, 0: Indicates the level of the interrupt currently allowed. Processes an interrupt only if its request level is higher than the value indicated by this bit.

IL1	IL0	Interrupt level	High-low
0	0	1	High
0	1	1	†
1	0	2	
1	1	3	Low = no interrupt

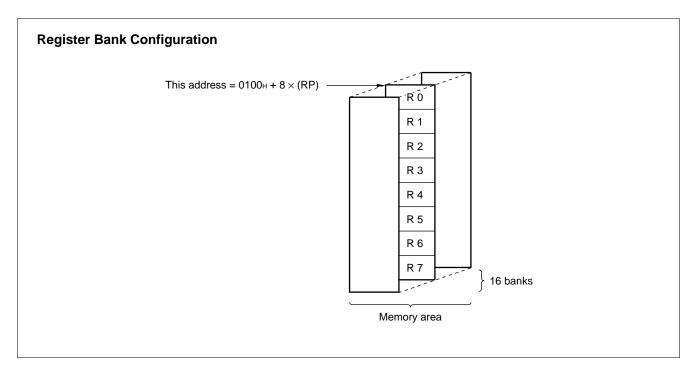
- N-flag: Set if the MSB is set to 1 as the result of an arithmetic operation. Cleared when the bit is set to 0.
- Z-flag: Set when an arithmetic operation results in 0. Cleared otherwise.
- V-flag: Set if the complement on 2 overflows as a result of an arithmetic operation. Reset if the overflow does not occur.
- C-flag: Set when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Cleared otherwise. Set to the shift-out value in the case of a shift instruction.

The following general-purpose registers are provided:

General-purpose registers: An 8-bit register for storing data

The general-purpose registers are 8 bits and located in the register banks of the memory. One bank contains eight registers and up to a total of 16 banks can be used on the MB89653AR (RAM 256×8 bits). The bank currently in use is indicated by the register bank pointer (RP).

Note: The number of register banks that can be used varies with the RAM size. Up to a total of 32 banks can be used on other than the MB89653AR.



■ I/O MAP

Address	Read/write	Register name	Register description		
00н	(R/W)	PDR0	Port 0 data register		
01н	(W)	DDR0	Port 0 data direction register		
02н	(R/W)	PDR1	Port 1 data register		
03н	(W)	DDR1	Port 1 data direction register		
04н	(R/W)	PDR2	Port 2 data register		
05н	(R/W)	DDR2	Port 2 data direction register		
06н		,	Vacancy		
07н	(R/W)	SCC	System clock control register		
08н	(R/W)	SMC	System mode control register		
09н	(R/W)	WDTC	Watchdog time control register		
ОАн	(R/W)	TBTC	Time-base timer control register		
0Вн	(R/W)	WCR	Watch prescaler control register		
0Сн	(R/W)	PDR3	Port 3 data register		
0Дн	(R/W)	DDR3	Port 3 data direction register		
0Ен	(R/W)	PDR4	Port 4 data register		
0Fн	(R/W)	DDR4	Port 4 data direction register		
10н	(R/W)	T4CR	Timer 4 control register		
11н	(R/W)	T3CR	Timer 3 control register		
12н	(R/W)	T4DR	Timer 4 data register		
13н	(R/W)	T3DR	Timer 3 data register		
14н			Vacancy		
15н			Vacancy		
16н	(R/W)	PDR5	Port 5 data register		
17н			Vacancy		
18н			Vacancy		
19н			Vacancy		
1Ан	(W)	ICR6	Port 6 input control register		
1Вн	(R)	PDR6	Port 6 data register		
1Сн	(R/W)	PDR7	Port 7 data register		
1Dн	(R/W)	CHG2	Port 2 switching register		
1Ен	(R/W)	CNTR1	PWM 0/1 control register		
1F _H	(W)	COMP1	PWM 0/1 compare register		

(Continued)

Address	Read/write	Register name	Register description					
20н	(R/W)	CNTR2	PWM 2/3 control register					
21н	(W)	COMP2	PWM 2/3 compare register					
22н		Vacancy						
23н			Vacancy					
24н	(R/W)	T2CR	Timer 2 control register					
25н	(R/W)	T1CR	Timer 1 control register					
26н	(R/W)	T2DR	Timer 2 data register					
27н	(R/W)	T1DR	Timer 1 data register					
28н	(R/W)	SMR	Serial mode register					
29н	(R/W)	SDR	Serial data register					
2Ан			Vacancy					
2Вн			Vacancy					
2Сн			Vacancy					
2Dн	(R/W)	ADC1	A/D converter control register 1					
2Ен	(R/W)	ADC2	A/D converter control register 2					
2Fн	(R/W)	ADCD	A/D converter data register					
30н	(R/W)	EIE1	External interrupt 1 enable register					
31н	(R/W)	EIF1	External interrupt 1 flag register					
32н	(R/W)	EIE2	External interrupt 2 enable register					
33н	(R/W)	EIF2	External interrupt 2 flag register					
34н to 5Fн			Vacancy					
60н to 6Fн	(R/W)	VRAM	Display data RAM					
70н	(R/W)	LCR1	LCD controller/driver control register 1					
71н	(R/W)	LCR2	LCD controller/driver control register 2					
72н	(R/W)	PDR8	Port 8 data register					
73н	(W)	DDR8	Port 8 data direction register					
74н to 7Bн			Vacancy					
7Сн	(W)	ILR1	Interrupt level setting register 1					
7Dн	(W)	ILR2	Interrupt level setting register 2					
7Е н	(W)	ILR3	Interrupt level setting register 3					
7 Fн		- 1	Vacancy					

Note: Do not use vacancies.

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

(AVss = Vss = 0.0 V)

Doromotor	Symbol	Va	lue	Unit	Remarks
Parameter	Symbol	Min	Max	Offic	Remarks
Power supply voltage	Vcc AVcc	Vss-0.3	Vss + 7.0	V	*1
A/D converter reference input voltage	AVR	Vss-0.3	Vss + 7.0	V	
LCD power supply voltage	V0 to V3	Vss-0.3	Vss + 7.0	V	V0 to V3 must not exceed Vcc.
Input voltage	Vı	Vss-0.3	Vcc + 0.3	V	Except P70 to P75*2
Imput voltage	V _{I2}	Vss - 0.3	Vss + 7.0	V	P70 to P75
Output voltage	Vo	Vss - 0.3	Vcc + 0.3	V	Except P70 to P75*2
Odiput voltage	V _{O2}	Vss - 0.3	Vss + 7.0	V	P70 to P75
"L" level maximum output current	lol	_	20	mA	
"L" level average output current	IOLAV	_	4	mA	Average value (operating current × operating rate)
"L" level total maximum output current	ΣΙοι	_	100	mA	
"L" level total average output current	Σ lolav		40	mA	Average value (operating current × operating rate)
"H" level maximum output current	Іон		-20	mA	
"H" level average output current	Іонач		-4	mA	Average value (operating current × operating rate)
"H" level total maximum output current	∑Іон	_	-50	mA	
"H" level total average output current	Σ Iohav	_	-20	mA	Average value (operating current × operating rate)
Power consumption	PD	_	300	mW	
Operating temperature	TA	-40	+85	°C	
Storage temperature	Tstg	- 55	+150	°C	

^{*1 :} Use AVcc and Vcc set at the same voltage.

Take care so that AVR does not exceed AVcc + 0.3 V and AVcc does not exceed Vcc, such as when power is turned on.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

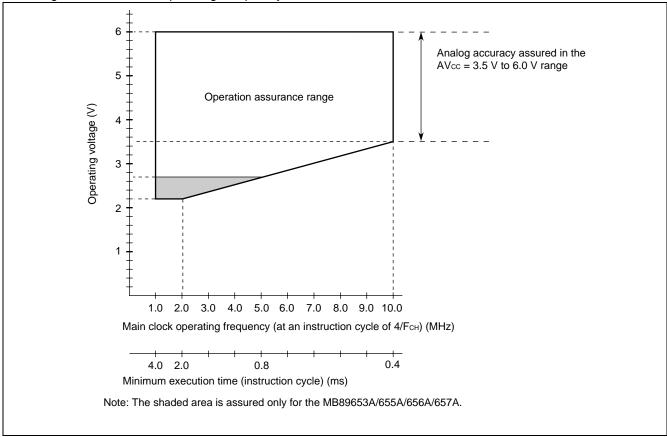
^{*2:} V_I and V_O must not exceed V_{CC} + 0.3 V.

2. Recommended Operating Conditions

(AVss = Vss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks		
Farameter	Syllibol	Min	Max	Oilit	Kemarks		
	.,	2.2*	6.0*	V	Normal operation assurance range* MB89653AR/655AR/656AR/657AR		
Power supply voltage	Vcc AVcc	2.7*	6.0*	V	Normal operation assurance range* MB89PV650A/P657A		
		1.5	6.0	V	Retains the RAM state in stop mode		
A/D converter reference input voltage	AVR	0.0	AVcc	V			
LCD power supply voltage	V0 to V3	Vss	Vcc	V	LCD power supply range (The optimum value is dependent on the LCD element in use.)		
Operating temperature	TA	-40	+85	°C			

*: These values vary with the operating frequency, instruction cycle, and analog assurance range. See "Operating Voltage vs. Main Clock Operating Frequency" and "5. A/D Converter Electrical Characteristics."



Operating Voltage vs. Main Clock Operating Frequency

"Operating Voltage vs. Main Clock Operating Frequency" indicates the operating frequency of the external oscillator at an instruction cycle of 4/FcH.

Since the operating voltage range is dependent on the instruction cycle, see minimum execution time if the operating speed is switched using a gear.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

> Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

> No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

3. DC Characteristics

 $(AVcc = Vcc = 5.0 \text{ V}, AVss = Vss = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Damamatan	Sym-	D:	O a maliti a m		Value		11	Damanla
Parameter	bol	Pin	Condition	Min	Тур	Max	Unit	Remarks
	V _{IH1}	P20 to P26, P30 to P37, P40 to P47, P60 to P67, P80 to P83	_	0.7 Vcc	_	Vcc + 0.3	V	
"Ll" lovel input	V _{IH2}	P72 to P75	_	0.7 Vcc	_	Vss + 6.0	V	Without pull-up resistor
"H" level input voltage	Vihs	P00 to P07, P10 to P17, RST, MOD0, MOD1, P26 (at SC input)	_	0.8 Vcc	_	Vcc + 0.3	V	
	V _{IHS2}	P70, P71	_	0.8 Vcc	_	Vss + 6.0	V	Without pull-up resistor
	VIL	P20 to P26, P30 to P37, P40 to P47, P60 to P67, P72 to P75, P80 to P83	_	Vss-0.3	_	0.3 Vcc	V	
"L" level input voltage	Vıs	P00 to P07, P10 to P17, P26 (at SC input), P70, P71, RST, MOD0, MOD1	_	Vss - 0.3	_	0.2 Vcc	V	
Open-drain output pin	VD	P24 to P26	_	Vss-0.3	_	Vss + 0.3	V	N-ch open-drain
application voltage	V _{D2}	P70 to P75	_	Vss-0.3	_	Vss + 6.0	V	
"H" level output voltage	Vон	P00 to P07, P10 to P17, P20 to P26, P30 to P37, P40 to P47, P50 to P57, P80 to P83	Iон = −2.0 mA	4.0	_	_	V	
"L" level output voltage	VoL	P00 to P07, P10 to P17, P20 to P26, P30 to P37, P40 to P47, P50 to P57, P70 to P75, P80 to P83	IoL = 4.0 mA	_	_	0.4	V	
Input leakage current (Hi-z output leakage current)	lu	P00 to P07, P10 to P17, P20 to P26, P30 to P37, P40 to P47, P60 to P67, P70 to P75, P80 to P83, MOD0, MOD1, RST		_	_	±5	μΑ	Without pull-up resistor
Pull-up resistance	Rpull	P00 to P07, P10 to P17, P20 to P26, P30 to P37, P40 to P47, P60 to P67, P70 to P75, P80 to P81	Vı = 0.0 V	25	50	100	kΩ	With pull-up resistor

 $(AVcc = Vcc = 5.0 \text{ V}, AVss = Vss = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Davamatar	Sym-	Dia		Condition		Value		1110:4	Remarks
Parameter	bol	Pin		Condition	Min	Тур	Max	Unit	Remarks
	Icc1		Vcc:	= 10 MHz = 5.0 V = 0.4 μs	_	12	20	mA	
	Icc2		Vcc	FcH = 10 MHz Vcc = 3.0 V $t_{inst}^{*2} = 6.4 \mu s$		1.0	2	mA	MB89653AR/ 655AR/656AR/ 657AR/ PV650A
			Linst	- 0.4 μ3	_	1.5	2.5	mA	MB89P657A
	Iccs ₁		node	$F_{CH} = 10 \text{ MHz}$ $V_{CC} = 5.0 \text{ V}$ $t_{inst}^{*2} = 0.4 \mu\text{s}$	_	3	7	mA	
	Iccs2		Sleep mode	$F_{CH} = 10 \text{ MHz}$ $V_{CC} = 3.0 \text{ V}$ $t_{inst}^{*2} = 6.4 \mu\text{s}$	_	0.5	1.5	mA	
	Iccl	Vcc	Vcc:	FcL = 32.768 kHz, Vcc = 3.0 V Subclock mode		50	100	μА	MB89653AR/ 655AR/656AR/ 657AR/ PV650A
D				_	500	700	μΑ	MB89P657A	
Power supply current*1	Iccls		FcL = 32.768 kHz, Vcc = 3.0 V Subclock sleep mode FcL = 32.768 kHz, Vcc = 3.0 V •Watch mode •Main clock stop mode at dual- clock system		_	15	50	μА	
	Ісст				_	3	15	μΑ	
	Іссн		• Su • Ma	+25°C bclock stop mode ain clock stop mode single- clock system	_	_	1	μΑ	
	IA	- AVcc	whe	= 10 MHz, n A/D version is vated	_	1.5	3	mA	
	Іан	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	T _A =	FcH = 10 MHz, TA = +25°C, when A/D conversion is stopped		_	1	μА	

(Continued)

 $(AVcc = Vcc = 5.0 \text{ V}, AVss = Vss = 0.0 \text{ V}, T_A = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C})$

Parameter	Sym-	Pin	Condition		Value		Unit	Remarks
Farameter	bol	FIII	Condition	Min	Тур	Max	Offic	Remarks
LCD divided resistance	RLCD		Between Vcc and V0 at Vcc = 5.0 V	300	500	750	kΩ	
COM0 to COM3 output impedance	Rvсом	COM0 to COM03	V1 to V3 = 5.0 V			2.5	kΩ	
SEG0 to SEG31 output impedance	Rvseg	SEG0 to SEG31	V 1 to V3 = 3.0 V			15	kΩ	
LCD controller/ driver leakage current	ILCDL	V0 to V3, COM0 to 3, SEG0 to SEG31	_		_	±1	μА	
Input capacitance	Cin	Other than AVcc, AVss, Vcc, and Vss	f = 1 MHz	_	10	_	pF	

^{*1 :} The power supply current is measured at the external clock.

Note: For pins which serve as the LCD and ports (P30 to P37, P40 to P47, and P80 to P81), see the port parameter when these pins are used as ports and the LCD parameter when they are used as LCD pins.

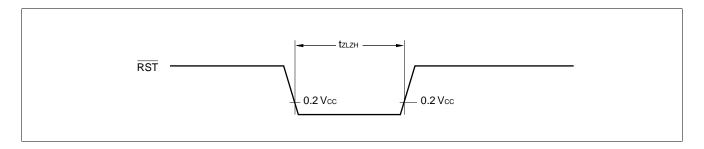
^{*2 :} For information on t_{inst}, see "(4) Instruction Cycle" in "4. AC Characteristics."

4. AC Characteristics

(1) Reset Timing

$$(Vcc = +5.0 V \pm 10\%, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$$

Parameter	Symbol	Condition	Valu	ne	Unit	Remarks
Parameter	Gyillboi	Condition	Min	Max	Oilit	Nemarks
RST "L" pulse width	t zlzh		48 t HCYL	_	ns	



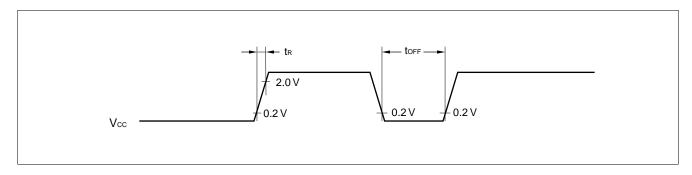
(2) Power-on Reset

$$(AVss = Vss = 0.0 V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C)$$

Parameter	Symbol	Condition	Val	ue	Unit	Remarks	
raidilietei	Symbol	Condition	Min	Max	Oilit		
Power supply rising time	t R		_	50	ms	Power-on reset function only	
Power supply cut-off time	toff 1 — n		ms	Due to repeated operations			

Note: Make sure that power supply rises within the selected oscillation stabilization time.

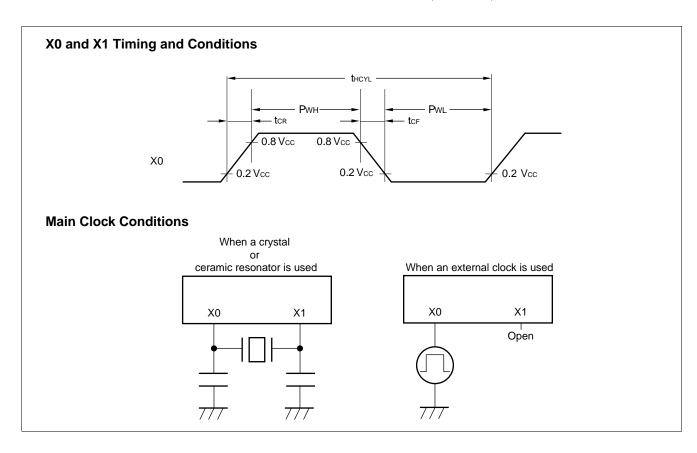
If power supply voltage needs to be varied in the course of operation, a smooth voltage rise is recommended.

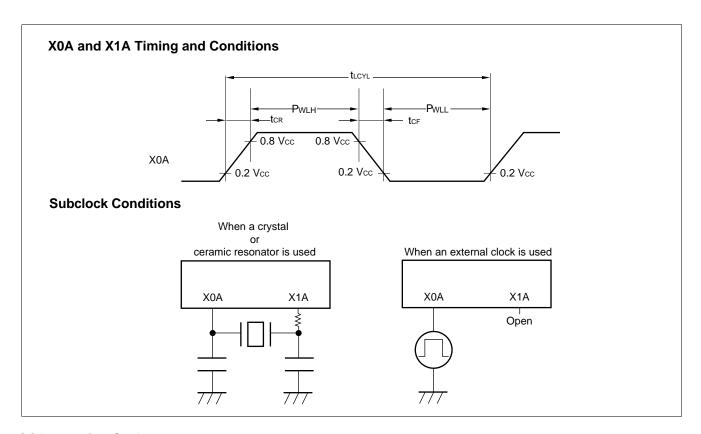


(3) Clock Timing

 $(AVss = Vss = 0.0 V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C)$

Parameter	Symbol	Pin	Condition		Value		Unit	Remarks	
Parameter	Syllibol	FIII	Condition	Min	Тур	Max	Oilit	Remarks	
Clock frequency	Fсн	X0, X1		1	_	10	MHz		
Clock frequency	FcL	X0A, X1A		_	32.768	_	kHz		
Clock cycle time	t HCYL	X0, X1		100	_	1000	ns		
Clock cycle time	t LCYL	X0A, X1A		_	30.5	_	μs		
Input clock pulse width	Pwh PwL	X0	_	20	_	_	ns	External clock	
Input clock pulse width	P _{WLH} P _{WLL}	X0A		_	15.2	_	μs	External clock	
Input clock rising/falling time	tcr tcr	X0		_	_	10	ns	External clock	





(4) Instruction Cycle

Parameter	Symbol	Value (typical)	Unit	Remarks
Instruction cycle (minimum execution time)	t inst	4/Гсн, 8/Гсн, 16/Гсн, 64/Гсн	μs	(4/FcH) $t_{inst} = 0.4 \mu s$ when operating at FcH = 10 MHz
		2/FcL	μs	$t_{\text{inst}} = 61.036~\mu \text{s}$ when operating at FcL = 32.768 kHz

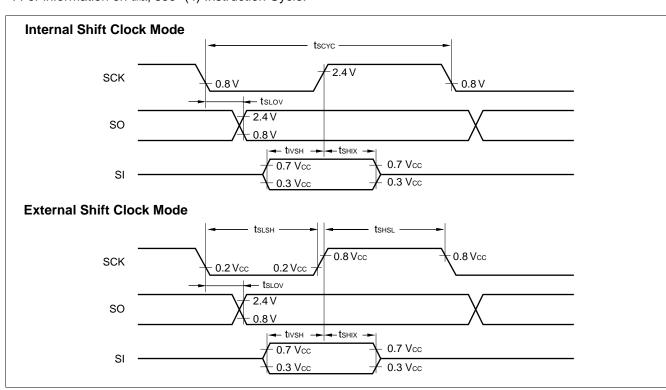
Note: When operating at 10 MHz, the cycle varies with the set execution time.

(5) Serial I/O Timing

 $(Vcc = +5.0 V\pm 10\%, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin	Condition	Value		Unit	Remarks
Farameter	Syllibol			Min	Max	Ullit	Remarks
Serial clock cycle time	tscyc	SCK	Internal shift clock mode	2 tinst*	_	μs	
$SCK \downarrow \to SO$ time	t sLov	SCK, SO		-200	200	ns	
Valid SI → SCK ↑	t ıvsH	SI, SCK		1/2 tinst*	_	μs	
$SCK \uparrow \to valid \; SI \; hold \; time$	t shix	SCK, SI		1/2 tinst*	_	μs	
Serial clock "H" pulse width	t shsl	SCK, SO SI, SCK SCK, SI	External shift clock mode	1 t inst*	_	μs	
Serial clock "L" pulse width	t slsh			1 tinst*	_	μs	
$SCK \downarrow \to SO$ time	tslov			0	200	ns	
Valid SI → SCK ↑	t ıvsH			1/2 tinst*	_	μs	
$SCK \uparrow \rightarrow valid SI hold time$	t shix			1/2 tinst*		μs	

^{*:} For information on tinst, see "(4) Instruction Cycle."

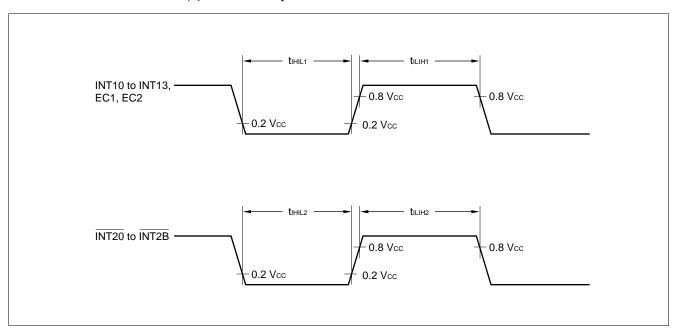


(6) Peripheral Input Timing

 $(Vcc = +5.0 V\pm 10\%, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin	Value		Unit	Remarks
Faranteter		FIII	Min	Max	Oilit	Nemarks
Peripheral input "H" pulse width 1	t _{ILIH1}	INT10 to INT13, EC1,	1 tinst*	_	μs	
Peripheral input "L" pulse width 1	t _{IHIL1}	EC2	1 tinst*	_	μs	
Peripheral input "H" pulse width 2	t _{ILIH2}	INT20 to INT2B	2 tinst*		μs	
Peripheral input "L" pulse width 2	t _{IHIL2}	INTZU (U INTZD	2 tinst*	1	μs	

^{*:} For information on tinst, see "(4) Instruction Cycle."



5. A/D Converter Electrical Characteristics

 $(AVcc = Vcc = +3.5 V to +6.0 V, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Sym- bol	Pin	Condition	Value			l lmi4	Damarka
				Min	Тур	Max	Unit	Remarks
Resolution	Vot VFST		_	_	_	8	bit	
Total error			AVR = AVcc	_	_	±1.5	LSB	
Linearity error				_	_	±1.0	LSB	
Differential linearity error				_	_	±0.9	LSB	
Zero transition voltage				AVss-1.0 LSB	AVss+0.5 LSB	AVss+2.0 LSB	mV	
Full-scale transition voltage				AVR – 3.0 LSB	AVR – 1.5 LSB	AVR	mV	
Interchannel disparity				_	_	0.5	LSB	
A/D mode conversion time			_	_	44 tinst*	_	μs	
Sense mode conversion time				_	12 tinst*	_	μs	
Analog port input current		AN0 to		_	_	10	μΑ	
Analog input voltage				0.0	_	AVR	V	
Reference voltage				0.0	_	AVcc	V	
Reference voltage supply current	lR	AVR	AVR = 5.0V, when A/D conversion is activated	_	100	_	μΑ	
	I RH		AVR = 5.0V, when A/D conversion is stopped	_	_	1	μА	

^{*:} For information on t_{inst}, see "(4) Instruction Cycle" in "4. AC Characteristics."

(1) A/D Glossary

• Resolution

Analog changes that are identifiable with the A/D converter.

When the number of bits is 8, analog voltage can be divided into $2^8 = 256$.

• Linearity error (unit: LSB)

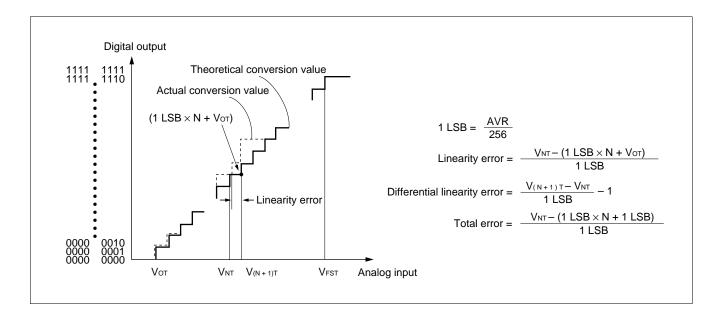
The deviation of the straight line connecting the zero transition point ("0000 0000" \leftrightarrow "0000 0001") with the full-scale transition point ("1111 1111" \leftrightarrow "1111 1110") from actual conversion characteristics

• Differential linearity error (unit: LSB)

The deviation of input voltage needed to change the output code by 1 LSB from the theoretical value

• Total error (unit: LSB)

The difference between theoretical and actual conversion values



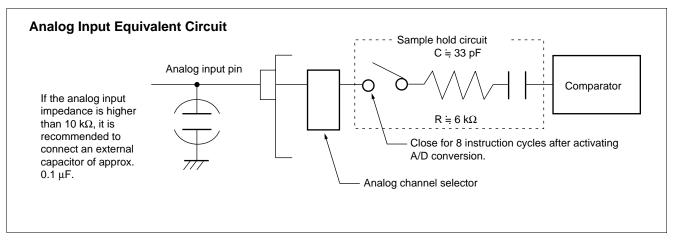
(2) Precautions

• Input impedance of the analog input pins

The A/D converter used for the MB89650AR series contains a sample hold circuit as illustrated below to fetch analog input voltage into the sample hold capacitor for eight instruction cycles after activating A/D conversion.

For this reason, if the output impedance of the external circuit for the analog input is high, analog input voltage might not stabilize within the analog input sampling period. Therefore, it is recommended to keep the output impedance of the external circuit low (below 10 k Ω).

Note that if the impedance cannot be kept low, it is recommended to connect an external capacitor of about 0.1 μ F for the analog input pin.

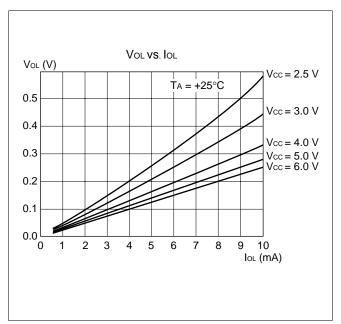


• Error

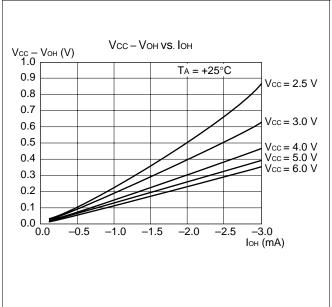
The smaller the | AVR - AVss |, the greater the error would become relatively.

■ EXAMPLE CHARACTERISTICS

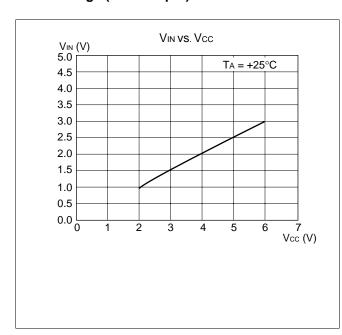
(1) "L" Level Output Voltage



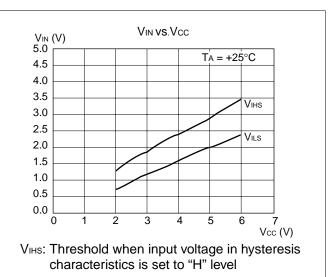
(2) "H" Level Output Voltage



(3) "H" Level Input Voltage/"L" Level Input Voltage (CMOS Input)

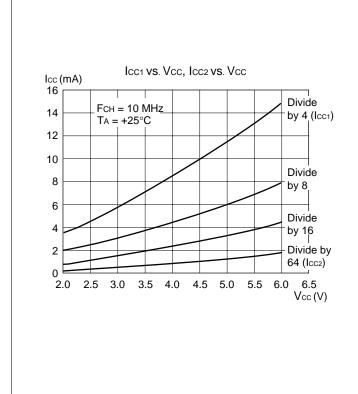


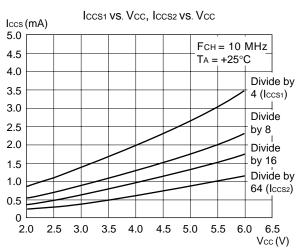
(4) "H" Level Input Voltage/"L" Level Input Voltage (Hysteresis Input)

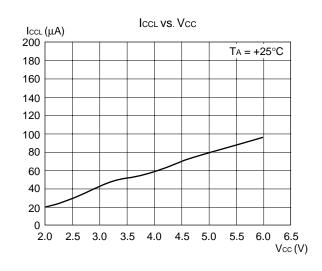


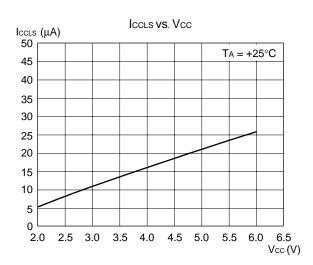
VILS: Threshold when input voltage in hysteresis characteristics is set to "L" level

(5) Power Supply Current (External Clock)



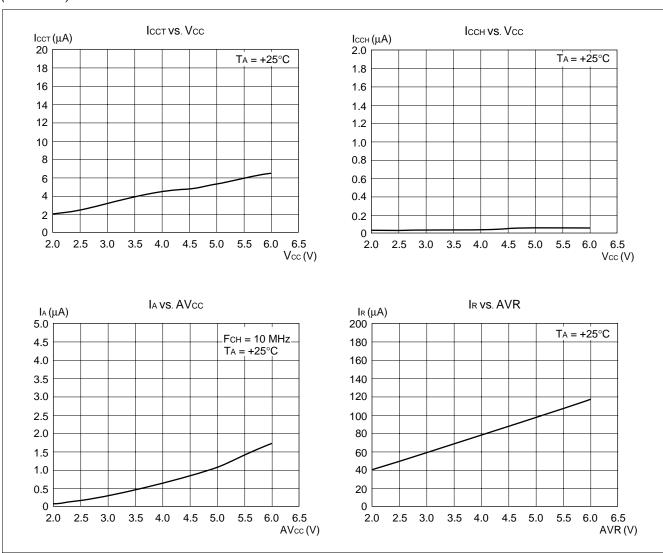




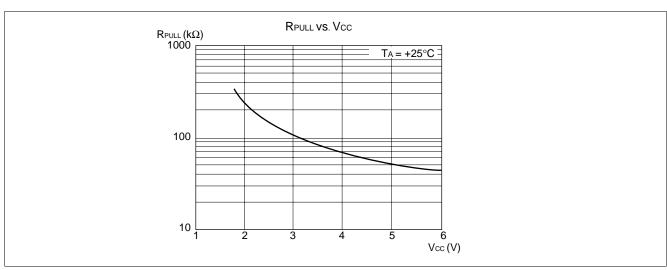


(Continued)

(Continued)



(6) Pull-up Resistance



■ MASK OPTIONS

No.	Part number	MB89653AR MB89655AR MB89656AR MB89657AR	MB89P657A	MB89PV650A
	Specifying procedure	Specify when ordering masking	Set with EPROM programmer	Setting not possible
1	Pull-up resistors P00 to P07, P10 to P17, P20 to P22, P24 to P26, P30 to P37, P40 to P47, P60 to P67, P70 to P75, P80 to P81	Specify by pin	Can be set per pin. (Select in a group of four bits for P14 to P17, P40 to P43, and P40 to P47.) (P75 to P70 are avail- able only for without a pull-up resistor.)	Fixed to without pull-up resistor
2	Power-on reset selection With power-on reset Without power-on reset	Selectable	With power-on reset	Fixed to with power-on reset
3	Selection of the oscillation stabilization time initial value Crystal oscillator: 2 ¹⁸ /FcH (Approx. 26.2 ms*1) Ceramic oscillator: 2 ¹³ /FcH (Approx. 26.2 ms*1)	Selectable	2 ¹⁸ /Fc н (Approx. 26.2 ms ^{*1})	Fixed to 2 ¹⁸ /F _{CH} (Approx. 26.2 ms*1)
4	Selection either single- or dual-clock system Single clock Dual clock	Selectable	Setting possible	Fixed to dual-clock system
5	Selection of a built-in booster*2 Without booster With booster (Segment output switching) 16 segments: Selection of P30 to P37 and P40 to P47 20 segments: Selection of P30 to P37 and P40 to P43 24 segments: Selection of P30 to P37 28 segments: Selection of P30 to P33 32 segments: No port selection	Selectable	Can be selected from the following six options: -101: Without booster -102: 16 segments -103: 20 segments -104: 24 segments -105: 28 segments -106: 32 segments	Fixed to without booster

^{*1 :} The value at FcH = 10 MHz

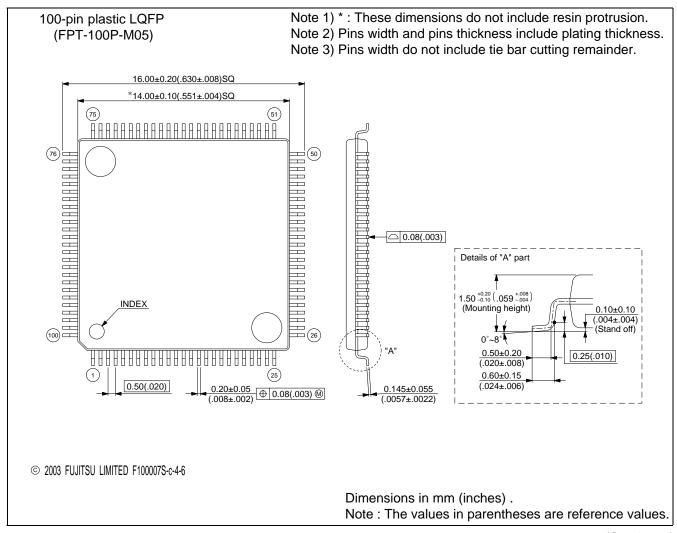
Note: Reset is input asynchronized with the internal clock whether with or without power-on reset.

^{*2 :} On microcontrollers with a built-in booster, only 1/3 bias can be used. The 1/2 duty cannot be used.

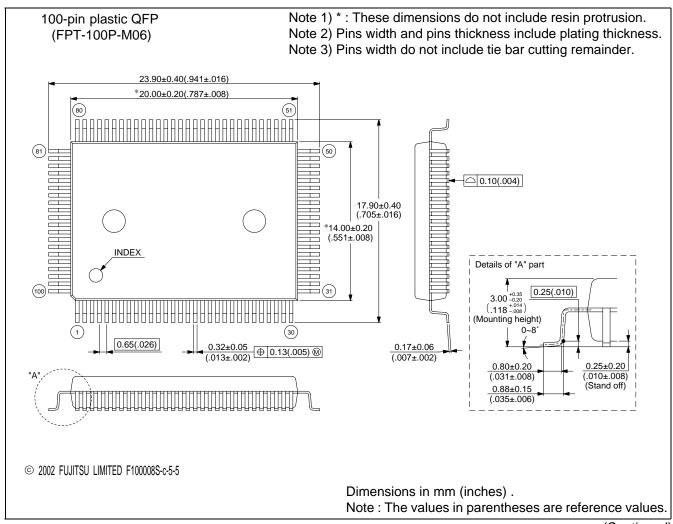
■ ORDERING INFORMATION

Part number	Package	Remarks
MB89653APFV MB89655APFV MB89656APFV MB89657APFV MB89P657APFV-101 MB89P657APFV-102 MB89P657APFV-103 MB89P657APFV-104 MB89P657APFV-105 MB89P657APFV-106	100-pin Plastic LQFP (FPT-100P-M05)	
MB89653APF MB89655APF MB89656APF MB89657APF MB89P657APF-101 MB89P657APF-102 MB89P657APF-103 MB89P657APF-104 MB89P657APF-105 MB89P657APF-106	100-pin Plastic QFP (FPT-100P-M06)	
MB89PV650ACF	100-pin Ceramic MQFP (MQP-100C-P02)	

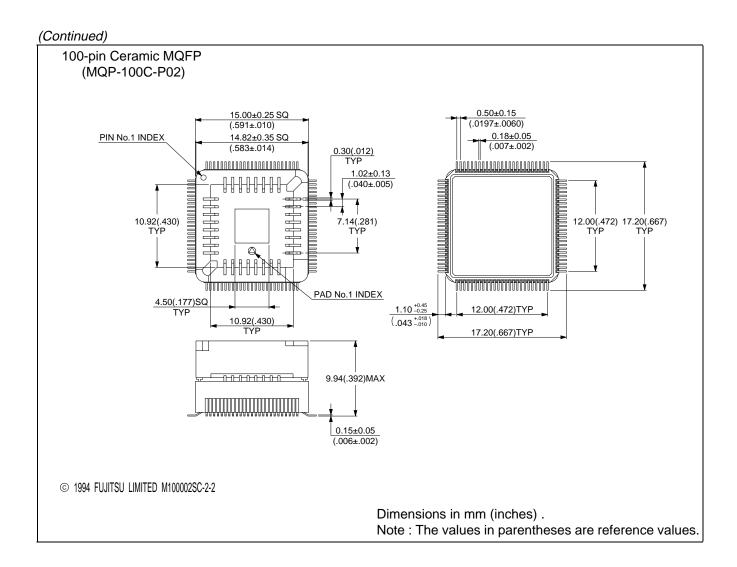
■ PACKAGE DIMENSIONS



(Continued)



(Continued)



FUJITSU LIMITED

All Rights Reserved.

The contents of this document are subject to change without notice. Customers are advised to consult with FUJITSU sales representatives before ordering.

The information, such as descriptions of function and application circuit examples, in this document are presented solely for the purpose of reference to show examples of operations and uses of Fujitsu semiconductor device; Fujitsu does not warrant proper operation of the device with respect to use based on such information. When you develop equipment incorporating the device based on such information, you must assume any responsibility arising out of such use of the information. Fujitsu assumes no liability for any damages whatsoever arising out of the use of the information.

Any information in this document, including descriptions of function and schematic diagrams, shall not be construed as license of the use or exercise of any intellectual property right, such as patent right or copyright, or any other right of Fujitsu or any third party or does Fujitsu warrant non-infringement of any third-party's intellectual property right or other right by using such information. Fujitsu assumes no liability for any infringement of the intellectual property rights or other rights of third parties which would result from the use of information contained herein.

The products described in this document are designed, developed and manufactured as contemplated for general use, including without limitation, ordinary industrial use, general office use, personal use, and household use, but are not designed, developed and manufactured as contemplated (1) for use accompanying fatal risks or dangers that, unless extremely high safety is secured, could have a serious effect to the public, and could lead directly to death, personal injury, severe physical damage or other loss (i.e., nuclear reaction control in nuclear facility, aircraft flight control, air traffic control, mass transport control, medical life support system, missile launch control in weapon system), or (2) for use requiring extremely high reliability (i.e., submersible repeater and artificial satellite).

Please note that Fujitsu will not be liable against you and/or any third party for any claims or damages arising in connection with above-mentioned uses of the products.

Any semiconductor devices have an inherent chance of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

If any products described in this document represent goods or technologies subject to certain restrictions on export under the Foreign Exchange and Foreign Trade Law of Japan, the prior authorization by Japanese government will be required for export of those products from Japan.

F0309